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1. (Currently Amended) An integrated circuit structure comprising:  
a carrier;  
a device connected to said carrier;  
solder connectors electrically connecting said device to said carrier;  
a compressible film surrounding sides of said solder connectors, wherein said compressible film has sufficient compressibility to accommodate expansion of said solder connections when said solder connections are melted without damaging said insulating material, wherein said compressible film is stable above the melting point of said solder connectors, and wherein said compressible film remains compressible through numerous thermal excursions; and  
an insulating material filling gaps between said carrier and said device.
2. (Canceled).
3. (Canceled).
4. (Original) The structure in claim 1, wherein said compressible film forms a pattern between said carrier and said device.
5. (Original) The structure in claim 4, wherein said pattern has channels between said device and said carrier, wherein said channels are filled with said insulating material.
6. (Original) The structure in claim 4, wherein said pattern comprises diagonal stripes of said compressible film.
7. (Original) The structure in claim 4, wherein said pattern comprises rectangles of said compressible film.
8. (Currently Amended) An integrated circuit structure comprising:  
a carrier;  
a device connected to said carrier;

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lead-free connectors electrically connecting said device to said carrier;

a compressible film surrounding sides of said lead-free connectors, wherein said compressible film has sufficient compressibility to accommodate expansion of said lead-free connections when said lead-free connections are melted without damaging said underfill, wherein said compressible film is stable above the melting point of said solder connectors, and wherein said compressible film remains compressible through numerous thermal excursions; and

an insulating underfill filling gaps between said carrier and said device.

9. (Canceled).

10. (Canceled).

11. (Original) The structure in claim 8, wherein said compressible film forms a pattern between said carrier and said device.

12. (Original) The structure in claim 11, wherein said pattern has channels between said device and said carrier, wherein said channels are filled with said underfill.

13. (Original) The structure in claim 11, wherein said pattern comprises diagonal stripes of said compressible film.

14. (Original) The structure in claim 11, wherein said pattern comprises rectangles of said compressible film.

15-28 (Cancelled).

29. (Currently Amended) An integrated circuit structure comprising:

a carrier;

a device connected to said carrier;

solder connectors electrically connecting said device to said carrier;

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a compressible film comprising one of a rubber and a foam surrounding sides of said solder connectors, wherein said compressible film is stable above the melting point of said solder connectors, and wherein said compressible film remains compressible through numerous thermal excursions; and

an insulating material filling gaps between said carrier and said device.

30. (Canceled).

31. (Previously Presented) The structure in claim 29, wherein said compressible film has sufficient compressibility to accommodate expansion of said solder connections when said solder connections are melted without damaging said insulating material.

32. (Previously Presented) The structure in claim 29, wherein said compressible film forms a pattern between said carrier and said device.

33. (Previously Presented) The structure in claim 32, wherein said pattern has channels between said device and said carrier, wherein said channels are filled with said insulating material.

34. (Previously Presented) The structure in claim 32, wherein said pattern comprises diagonal stripes of said compressible film.

35. (Previously Presented) The structure in claim 32, wherein said pattern comprises rectangles of said compressible film.